(54) Title: SUBSTRATE BASED UNMOLDED PACKAGE

(57) Abstract: A semiconductor die package is disclosed. In one embodiment, the semiconductor die package has a substrate. It includes (i) a lead frame structure including a die attach region with a die attach surface and a lead having a lead surface, and (ii) a molding material. The die attach surface and the lead surface are exposed through the molding material. A semiconductor die is on the die attach region, and the semiconductor die is electrically coupled to the lead.
as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii)) for all designations

of inventorship (Rule 4.17(iv)) for US only

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INTERNATIONAL SEARCH REPORT

A. CLASSIFICATION OF SUBJECT MATTER
IPC(Y): H01L 28/495
US CL: 437/666
According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED
Minimum documentation searched (classification system followed by classification symbols)
U.S.: 927/666, 737, 704, 78

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

NONE

Electronic database consulted during the international search (name of database and, where practical, search terms used)
EAST
search terms: lead frame, die, chip, source, gate, drain, mosfet

C. DOCUMENTS CONSIDERED TO BE RELEVANT

<table>
<thead>
<tr>
<th>Category</th>
<th>Citation of document, with indication, where appropriate, of the relevant passages</th>
<th>Relevant to claim No.</th>
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<tbody>
<tr>
<td>Y</td>
<td></td>
<td>22-25</td>
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☐ Further documents are listed in the continuation of Box C. ☐ See patent family annex.

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Date of the actual completion of the international search: 06 NOVEMBER 2003

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